

# Media Resistant and High Temperature Accuracy Integrated Silicon Pressure Sensor for Measuring Absolute Pressure, On-Chip Signal Conditioned, Temperature Compensated and Calibrated

The Freescale MPXHZ6400A series sensor integrates on-chip, bipolar op amp circuitry and thin film resistor networks to provide a high output signal and temperature compensation. The small form factor and high reliability of on-chip integration make the Freescale pressure sensor a logical and economical choice for the system designer.

The MPXHZ6400A series piezoresistive transducer is a state-of-the-art, monolithic, signal conditioned, silicon pressure sensor. This sensor combines advanced micromachining techniques, thin film metallization, and bipolar semiconductor processing to provide an accurate, high level analog output signal that is proportional to applied pressure.

Figure 1 shows a block diagram of the internal circuitry integrated on a pressure sensor chip.

## Features

- Improved Accuracy at High Temperature
- Available in Small and Super Small Outline Packages
- 1.5% Maximum Error over 0° to 85°C
- Ideally suited for Microprocessor or Microcontroller-Based Systems
- Temperature Compensated from -40° to +125°C
- Durable Thermoplastic (PPS) Surface Mount Package

## Typical Applications

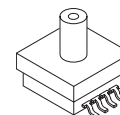
- Industrial Controls
- Engine Control/Liquified Petroleum Gas (LPG)

ORDERING INFORMATION					
Device Type	Options	Case No.	MPX Series Order No.	Packing Options	Device Marking
Ported Element	Absolute, Axial Port	1317A	MPXHZ6400AC6T1	Tape & Reel	MPXHZ6400A

**MPXHZ6400A**

**INTEGRATED PRESSURE SENSOR**  
 20 TO 400 kPA (3.0 TO 58 psi)  
 0.2 TO 4.8 V OUTPUT  
 (3.0 TO 58 psi)

## SUPER SMALL OUTLINE PACKAGE

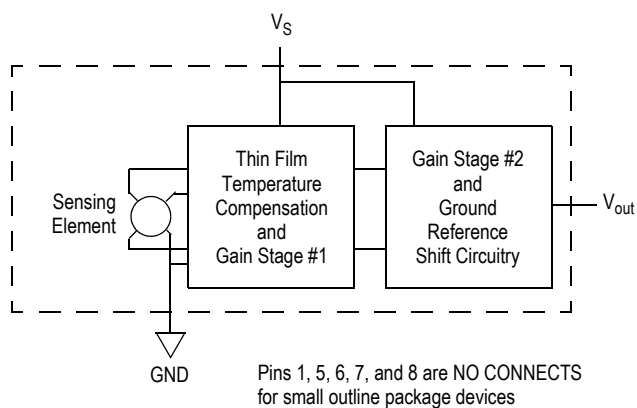


**MPXHZ6400AC6T1**  
**CASE 1317A-03**

## PIN NUMBERS<sup>(1)</sup>

1	N/C	5	N/C
2	V <sub>S</sub>	6	N/C
3	GND	7	N/C
4	V <sub>OUT</sub>	8	N/C

1. Pins 1, 5, 6, 7, and 8 are internal device connections. Do not connect to external circuitry or ground. Pin 1 is noted by the notch in the lead.



**Figure 1. Fully Integrated Pressure Sensor Schematic**

**Table 1. Maximum Ratings<sup>(1)</sup>**

Rating	Symbol	Value	Unit
Maximum Pressure	$P_{MAX}$	1600	kPa
Storage Temperature	$T_{STG}$	-40° to +125°	°C
Operating Temperature	$T_A$	-40° to +125°	°C
Output Source Current @ Full Scale Output <sup>(2)</sup>	$I_{o+}$	0.5	mAdc
Output Sink Current @ Minimum Pressure Offset <sup>2</sup>	$I_{o-}$	-0.5	mAdc

1. Exposure beyond the specified limits may cause permanent damage or degradation to the device.
2. Maximum Output Current is controlled by effective impedance from  $V_{out}$  to GND or  $V_{out}$  to  $V_S$  in the application circuit.

**Table 2. Operating Characteristics** ( $V_S = 5.0 \text{ Vdc}$ ,  $T_A = 25^\circ\text{C}$ .)

Characteristic	Symbol	Min	Typ	Max	Unit
Pressure Range	$P_{OP}$	20	—	400	kPa
Supply Voltage <sup>(1)</sup>	$V_S$	4.64	5.0	5.36	Vdc
Supply Current	$I_o$	—	6.0	10	mAdc
Minimum Pressure Offset @ $V_S = 5.0 \text{ Volts}$ <sup>(2)</sup>	$V_{off}$	0.133	0.2	0.267	Vdc
Full Scale Output @ $V_S = 5.0 \text{ Volts}$ <sup>(3)</sup>	$V_{FSO}$	4.733	4.8	4.866	Vdc
Full Scale Span @ $V_S = 5.0 \text{ Volts}$ <sup>(4)</sup>	$V_{FSS}$	4.467	4.6	4.733	Vdc
Accuracy <sup>(5)</sup>	—	—	—	$\pm 1.5$	$\%V_{FSS}$
Sensitivity	V/P	—	12.1	—	mV/kPa
Response Time <sup>(6)</sup>	$t_R$	—	1.0	—	ms
Warm-Up Time <sup>(7)</sup>	—	—	20	—	ms
Offset Stability <sup>(8)</sup>	—	—	$\pm 0.25$	—	$\%V_{FSS}$

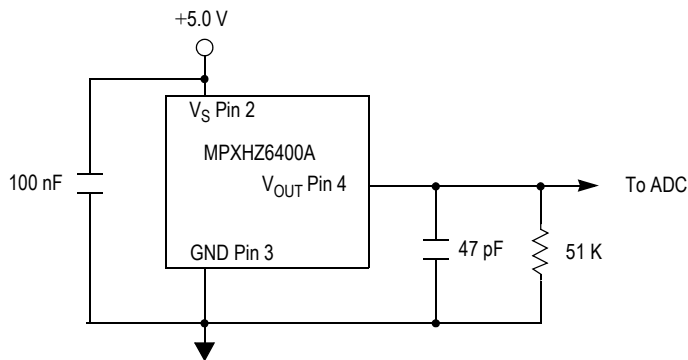
1. Device is ratiometric within this specified excitation range.
2. Offset ( $V_{off}$ ) is defined as the output voltage at the minimum rated pressure.
3. Full Scale Output ( $V_{FSO}$ ) is defined as the output voltage at the maximum or full rated pressure.
4. Full Scale Span ( $V_{FSS}$ ) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.
5. Accuracy is the deviation in actual output from nominal output over the entire pressure range and temperature range as a percent of span at  $25^\circ\text{C}$  due to all sources of error including the following:
  - Linearity: Output deviation from a straight line relationship with pressure over the specified pressure range.
  - Temperature Hysteresis: Output deviation at any temperature within the operating temperature range, after the temperature is cycled to and from the minimum or maximum operating temperature points, with zero differential pressure applied.
  - Pressure Hysteresis: Output deviation at any pressure within the specified range, when this pressure is cycled to and from the minimum or maximum rated pressure, at  $25^\circ\text{C}$ .
  - TcSpan: Output deviation over the temperature range of 0 to  $85^\circ\text{C}$ , relative to  $25^\circ\text{C}$ .
  - TcOffset: Output deviation with minimum rated pressure applied, over the temperature range of 0 to  $85^\circ\text{C}$ , relative to  $25^\circ\text{C}$ .
  - Variation from Nominal: The variation from nominal values, for Offset or Full Scale Span, as a percent of  $V_{FSS}$ , at  $25^\circ\text{C}$ .
6. Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.
7. Warm-up Time is defined as the time required for the product to meet the specified output voltage after the Pressure has been stabilized.
8. Offset Stability is the product's output deviation when subjected to 1000 hours of Pulsed Pressure, Temperature Cycling with Bias Test.

Figure 2 illustrates a typical application circuit (output source current operation).

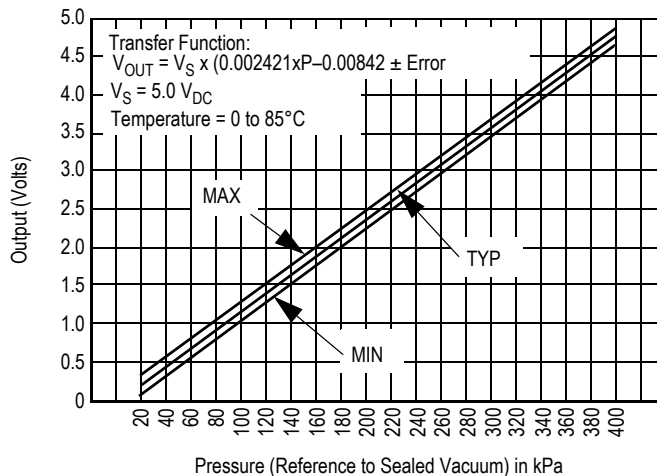
Figure 3 shows the sensor output signal relative to pressure input. Typical minimum and maximum output curves are shown for operation over 0 to 85°C temperature range. The output will saturate outside of the rated pressure range.

A gel die coat isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be

transmitted to the silicon diaphragm. The MPXHZ6400A series pressure sensor operating characteristics, internal reliability and qualification tests are based on use of dry air as the pressure media. Media other than dry air may have adverse effects on sensor performance and long-term reliability. Contact the factory for information regarding media compatibility in your application.



**Figure 2. Typical Application Circuit (Output Source Current Operation)**

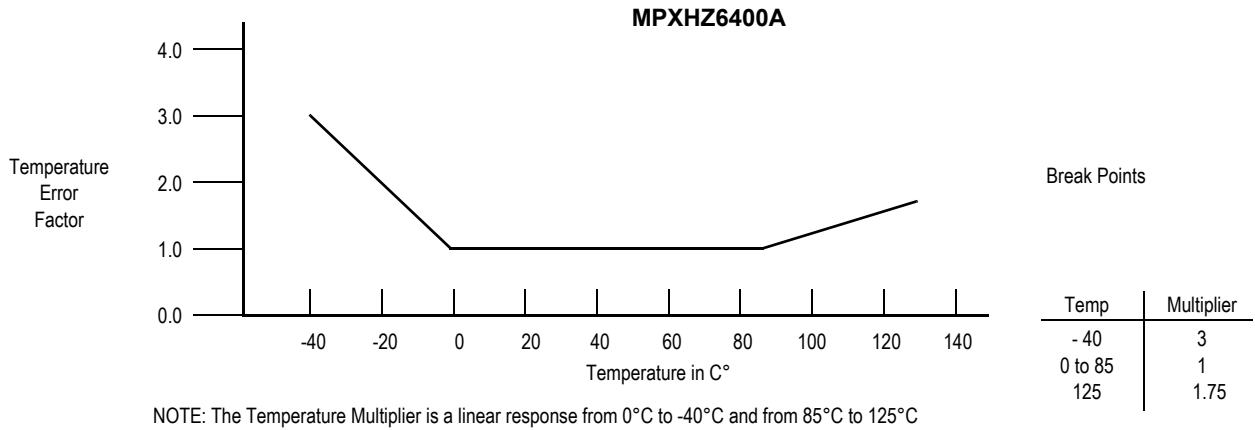


**Figure 3. Output versus Absolute Pressure**

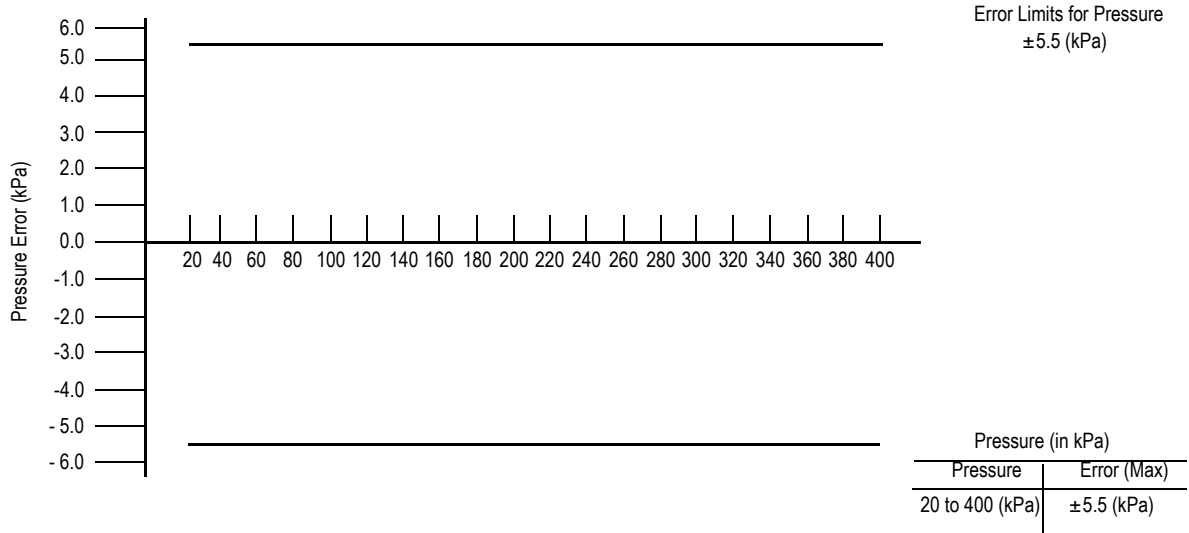
### Transfer Function (MPXHZ6400A)

**Normal Transfer Value:**  $V_{OUT} = V_S \times (0.002421 \times P - 0.00842)$   
 $\pm$  Pressure Error  $\times$  Temp. Factor  $\times 0.002421 \times V_S$   
 $V_S = 5.0 \pm 0.36 V_{DC}$

### Temperature Error Band



### Pressure Error Band



## SURFACE MOUNTING INFORMATION

### Minimum Recommended Footprint for Super Small Outline Packages

Surface mount board layout is a critical portion of the total design. The footprint for the semiconductor package must be the correct size to ensure proper solder connection interface between the board and the package. With the correct pad geometry, the packages will self-align when subjected to a solder reflow process. It is always recommended to fabricate boards with a solder mask layer to avoid bridging and/or shorting between solder pads, especially on tight tolerances and/or tight layouts.

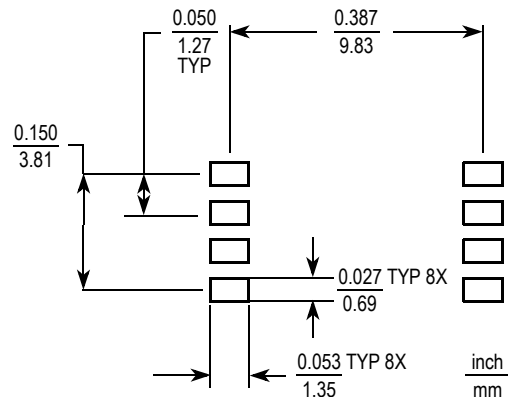
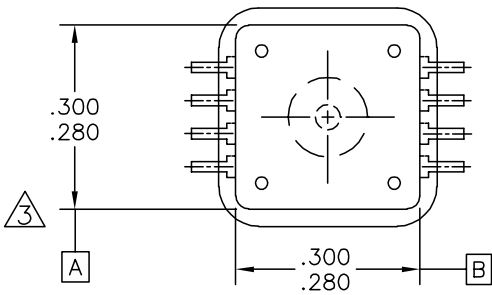
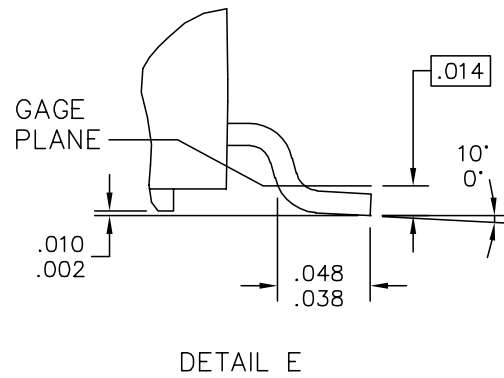
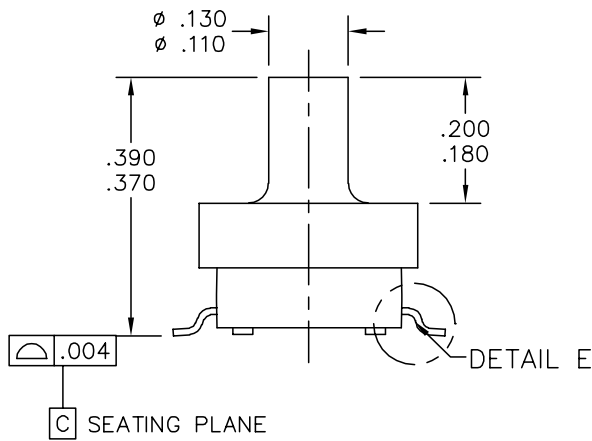
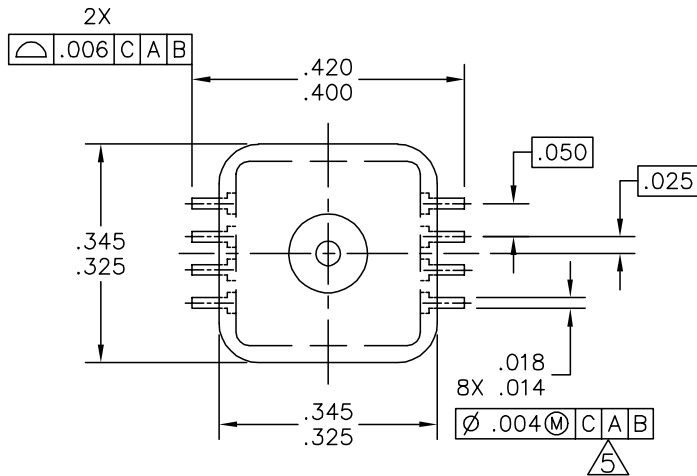


Figure 4. SSOP Footprint (Case 1317A)

# PACKAGE DIMENSIONS



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TITLE:  8 LD, PORTED SSOP	DOCUMENT NO: 98ARH99089A	REV: C	
	CASE NUMBER: 1317A-03	24 MAY 2005	
	STANDARD: NON-JEDEC		

PAGE 1 OF 2

**CASE 1317A-03  
ISSUE C  
SUPER SMALL OUTLINE PACKAGE**

## PACKAGE DIMENSIONS

NOTES:

1. ALL DIMENSIONS IN INCHES.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.  
MOLD FLASH OR PROTRUSION SHALL NOT EXCEED .006 INCHES PER SIDE.
4. ALL VERTICAL SURFACES TO BE 5° MAXIMUM.
5. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION.  
ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 INCHES MAXIMUM.

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	STANDARD: NON-JEDEC	

PAGE 2 OF 2

**CASE 1317A-03**  
**ISSUE C**  
**SUPER SMALL OUTLINE PACKAGE**

**MPXHZ6400A**

## **How to Reach Us:**

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www.freescale.com

### **E-mail:**

support@freescale.com

### **USA/Europe or Locations Not Listed:**

Freescale Semiconductor  
Technical Information Center, CH370  
1300 N. Alma School Road  
Chandler, Arizona 85224  
+1-800-521-6274 or +1-480-768-2130  
support@freescale.com

### **Europe, Middle East, and Africa:**

Freescale Halbleiter Deutschland GmbH  
Technical Information Center  
Schatzbogen 7  
81829 Muenchen, Germany  
+44 1296 380 456 (English)  
+46 8 52200080 (English)  
+49 89 92103 559 (German)  
+33 1 69 35 48 48 (French)  
support@freescale.com

### **Japan:**

Freescale Semiconductor Japan Ltd.  
Headquarters  
ARCO Tower 15F  
1-8-1, Shimo-Meguro, Meguro-ku,  
Tokyo 153-0064  
Japan  
0120 191014 or +81 3 5437 9125  
support.japan@freescale.com

### **Asia/Pacific:**

Freescale Semiconductor Hong Kong Ltd.  
Technical Information Center  
2 Dai King Street  
Tai Po Industrial Estate  
Tai Po, N.T., Hong Kong  
+800 2666 8080  
support.asia@freescale.com

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